

Find out more



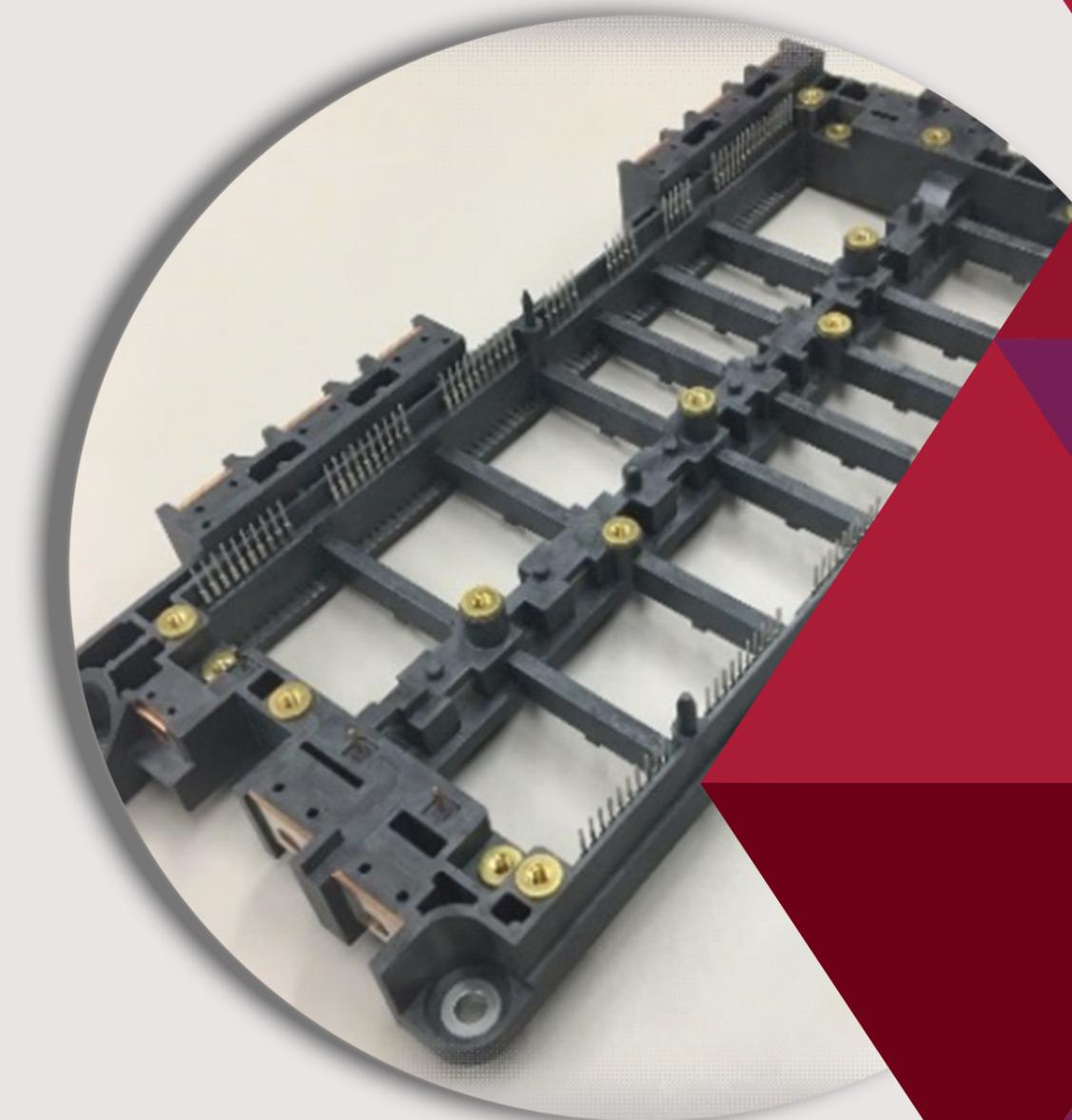
Miniaturization & Weight Reduction for Battery Application

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In-Mold Connecting Technology

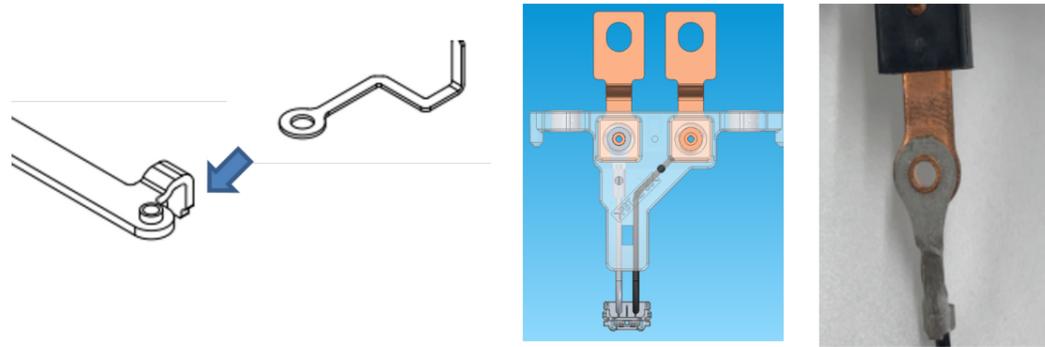
Our method of connecting busbar and wire is to use swaging technique in the insert molding process. The clamping press to connect and fasten busbar and wire is completed during the molding process so we can offer an effective and faster solution to assemble your parts.

Applications

- » Power module
- » Terminal assembly
- » Busbar assembly parts where current flows

Features

- » In-mold swaging technology
- » Enabling to use a wide range of metals
- » Enable to use different sizes of thickness
- » Reduction of connecting process to save time and cost



Metal Insert Mold

Miniaturization and weight reduction are so important factors in car manufacturing due to the tightening of CO₂ emission regulations as well as emerging EVs in which OEM always seek lightweighting to extend a longer cruising range.

We design and make the shape of insert mold with resin/metal composite, to fit your needs and to achieve your goal of miniaturization and weight reduction.

Applications

- » Inverter
- » Motor
- » Battery module
- » Battery disconnect unit
- » On board charger etc.

Features

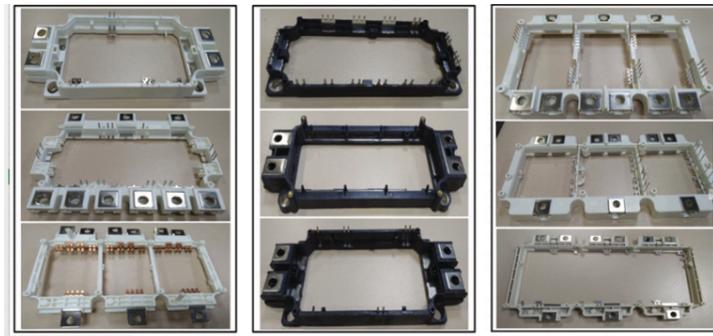
- » Providing multiple resin and metal parts as an integrated product by insert molding
- » Providing multiple insert molded products as one part
- » Designing enough creepage distances for insulation but ensuring desired mold shape for your needs
- » Advanced production technology to ensure customer's serial production steadily
- » Flexible approach to increase molds and machine to respond to the rapid increase in customer's demand

Ultra-Low Inductance Busbar

Achieving ultra-low inductance with super narrowed gap between busbars.

Applications

- » Power module
- » Inverter terminal assembly
- » Smoothing capacitors, etc.



Features

- » Insulation design with a 100 μm gap between busbars
- » Reducing parasitic inductance by making the PN terminals as close as possible
- » Insulation kept by film insert molding
- » Very effective for high-speed switching such as SiC
- » Miniaturisation for module
- » Patent pending

